

## IN THE CLAIMS:

In accordance with the Revised Rules under 37 C.F.R. 1.121, please amend the claims as shown below and indicated as “currently amended.” Also shown below are claims that may be original, cancelled, withdrawn, previously presented, new, and not entered.

1. (currently amended) A method for mounting through an adhesive sheet an electronic component on a printed circuit board provided with a wiring pattern, the method comprising the steps of:

heating air intervening between the adhesive sheet and the printed circuit board; and bonding, while heating the air, the adhesive sheet to an area of the printed circuit board to be mounted with the electronic component ~~in the above state~~.

2. (currently amended) The method ~~for mounting the electronic component~~ according to claim 1, wherein the air intervening between the adhesive sheet and the printed circuit board is heated upon heating the printed circuit board.

3. (currently amended) The method ~~for mounting the electronic component~~ according to claim 2, wherein the electronic component is pressurized and bonded~~thermally bonded on to~~ the adhesive sheet after the printed circuit board bonded with the adhesive sheet is cooled ~~down~~.

4. (currently amended) The method for mounting the electronic component according to claim 1, wherein ~~the heating temperature of the heating process~~ is set to a range between equal to or higher to not less than 60 degrees Celsius and equal to or loweressnor more than a reaction temperature of the adhesive sheet.

5. (currently amended) The method for mounting the electronic component according to ~~any one of claim 1, claim 2, claim 3, and or claim 4~~, wherein the adhesive sheet is defined as made of an anisotropic conductive film.

6. (currently amended) The method for mounting the electronic component according to ~~any one of claim 1, claim 2, claim 3, and or claim 4~~, wherein the printed circuit board is defined as made of a flexible board.